

HC260N075H6Y

750V N-Channel SiC Power MOSFET

Product features/产品特点

- Top side cooling technology
顶部散热技术
- High blocking voltage with low on-resistance
高反向耐压及低导通电阻
- High-speed switching with low capacitances
低电容实现的快速开关特性
- Fast Reverse Recovery
快速反向恢复特性
- Avalanche Ruggedness
出色的雪崩耐受能力
- High Temperature Operation Capability $T_{vj}=175^{\circ}\text{C}$
具备优异的耐高温工作能力（结温最高可达175°C）
- Halogen free, RoHS compliant
无卤，符合RoHS

Applications/应用领域

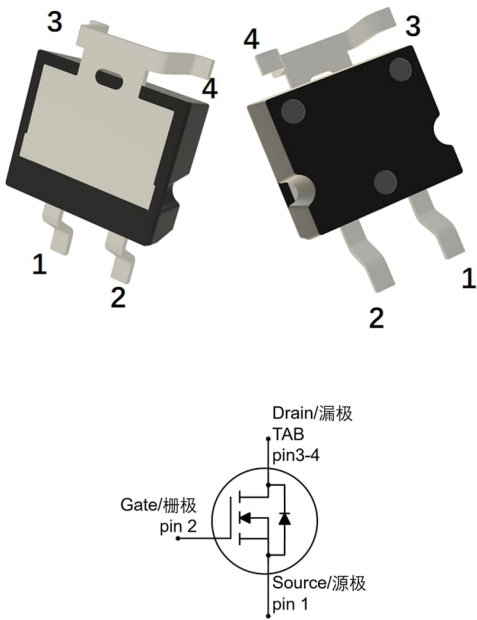
- Switch mode power supplies
开关电源
- Electric Vehicle Charging Stations
电动汽车充电桩
- Solar Inverters
光伏逆变器
- DC/DC converters
DC/DC 转换器

Key performance parameters/关键性能参数

Parameter	Value	Unit
V_{DSS}	750	V
$R_{DS(on),typ}$ $V_{GS}=15V$	256	mΩ
I_{DM}	23	A

Package parameters/封装信息

Type/型号	Package/封装	Marking/标识	Packaging method/包装方式
HC260N075H6Y	TSC263-4L	HC260N075Y	800pcs-Tape&Reel/卷带包装(单卷800颗)



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1. Maximum ratings at $T_{vj}=25^{\circ}\text{C}$, unless otherwise specified.

最大额定值 默认 $T_{vj}=25^{\circ}\text{C}$ 除非另有说明

Table 1 Maximum ratings/最大额定值

Parameter 参数	Symbol 符号	Test conditions 测试条件	Value 值	Unit 单位
Drain-source voltage 漏极-源极电压	V_{DSS}	$T_{vj}\geq 25^{\circ}\text{C}$	750	V
Drain current ¹ 连续漏极电流	I_D	$T_C=25^{\circ}\text{C}$	9	A
		$T_C=100^{\circ}\text{C}$	6	
Peak drain current ² 峰值漏极电流	I_{DM}	$T_C=25^{\circ}\text{C}$	23	A
Continuous diode current ¹ 连续二极管电流	I_S	$T_C=25^{\circ}\text{C}, V_{GS}=0\text{V}$	8	A
Peak diode current ² 峰值二极管电流	I_{SM}	$T_C=25^{\circ}\text{C}$	23	A
Maximum gate source voltage 栅源最大电压	$V_{GS,MAX}$		-10~22	V
Recommend gate source voltage 推荐的栅源电压	$V_{GS,op}$		0~15, 18	V
Power dissipation 总耗散功率	P_{tot}	$T_C=25^{\circ}\text{C}$	44	W
		$T_C=100^{\circ}\text{C}$	22	

1. Limited by $T_{vj(max)}$ /受限于最大结温

2. Pulse width t_p limited by $T_{vj(max)}$ /脉宽受限于最大结温



2. Thermal characteristics
热特性

Table 2 Thermal characteristics/热特性

Parameter 参数	Symbol 符号	Test conditions 测试条件	Value/值			Unit 单位
			Min.	Typ.	Max.	
Storage Temperature 存储温度	T _{stg}		-55		175	°C
Operating junction Temperature 工作结温	T _{vj}		-55		175	°C
Thermal resistance, junction-case 结-壳热阻	R _{th(j-c)}				3.4	°C/W
Thermal resistance, junction-ambient 结-环境热阻	R _{th(j-a)}			30		°C/W
Soldering temperature, reflow solderin 焊接温度，回流焊	T _{sold}	reflow MSL1			260	°C



3. Electrical characteristics at $T_{vj}=25^{\circ}\text{C}$, unless otherwise specified.

电气特性 默认 $T_{vj}=25^{\circ}\text{C}$ 除非另有说明

Table 3 Static characteristics/静态特性

Parameter 参数	Symbol 符号	Test conditions 测试条件	Value/值			Unit 单位
			Min.	Typ.	Max.	
Drain-source breakdown voltage 漏源击穿电压	$V_{(BR)DSS}$	$I_D=100\mu\text{A}, V_{GS}=0\text{V}$	750			V
Gate threshold voltage 门极开启阈值电压	$V_{GS(th)}$	$I_D=0.5\text{mA}, V_{DS}=V_{GS}$	$T_{vj}=25^{\circ}\text{C}$	3	4.1	5
			$T_{vj}=175^{\circ}\text{C}$		3.2	
Drain-source on-state resistance 漏极-源极导通电阻	$R_{DS(on)}$	$I_D=5\text{A}, V_{GS(on)}=15\text{V}$	$T_{vj}=25^{\circ}\text{C}$		256	330
			$T_{vj}=175^{\circ}\text{C}$		381	
		$I_D=5\text{A}, V_{GS(on)}=18\text{V}$	$T_{vj}=25^{\circ}\text{C}$		207	270
			$T_{vj}=175^{\circ}\text{C}$		352	
Zero gate voltage drain current 集电极-发射极漏电流	I_{DSS}	$V_{DS}=750\text{V}, V_{GS}=0\text{V}$	$T_{vj}=25^{\circ}\text{C}$		0.3	50
			$T_{vj}=175^{\circ}\text{C}$		1	
Gate to source Leakage current 门极-源极漏电流	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=22\text{V}$			100	nA
		$V_{DS}=0\text{V}, V_{GS}=-10\text{V}$	-100			
Forward transconductance 正向跨导	g_{fs}	$I_D=5\text{A}, V_{DS}=20\text{V}$		3.2		S
Integrated gate resistor 内部门极电阻	R_G	$f=1\text{MHz}$		16		Ω

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Table 4 Dynamic characteristics/动态特性

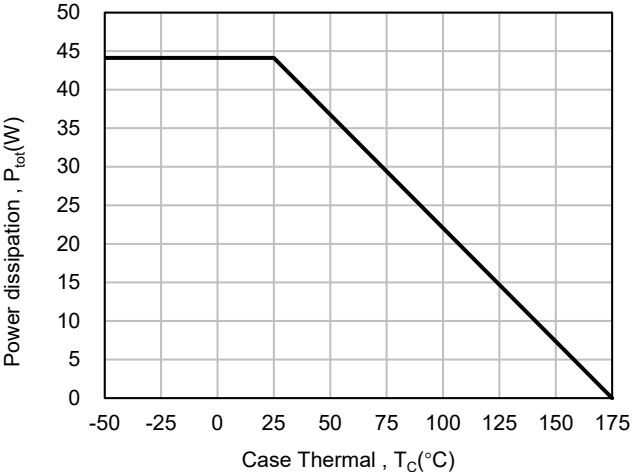
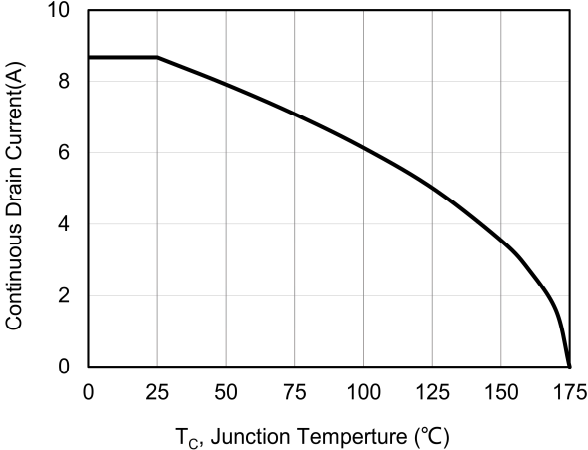
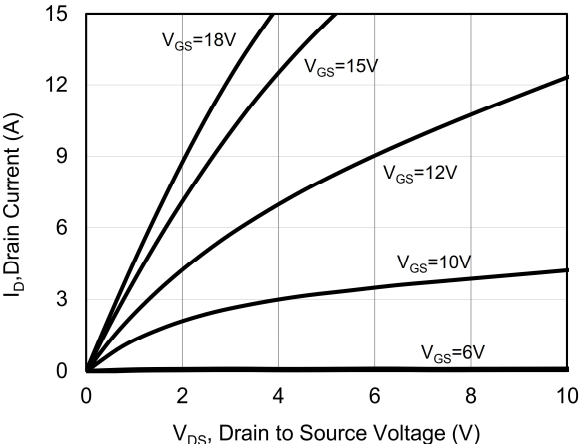
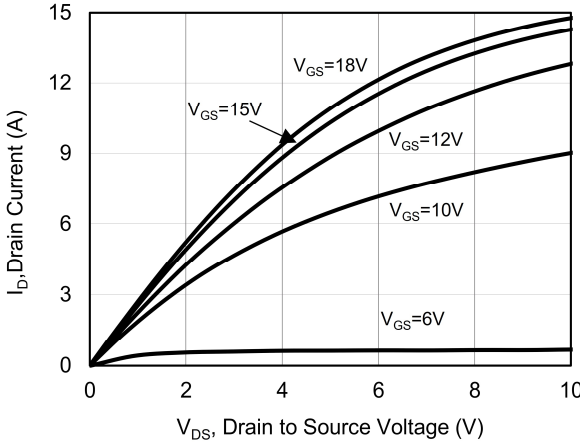
Parameter 参数	Symbol 符号	Test conditions 测试条件		Value/值			Unit 单位
				Min.	Typ.	Max.	
Input capacitance 输入电容	C _{iss}	V _{DS} =500V, V _{GS} =0V, f=100kHz			212		pF
Output capacitance 输出电容	C _{oss}				14		
Reverse transfer capacitance 反向传输电容	C _{rss}				1.3		
Coss stored energy 输出电容存储能量	E _{oss}	Calculated based on C _{oss}			2.1		μJ
Total gate charge 总栅极电荷	Q _{G(tot)}	V _{DD} =400V, I _D =5A, V _{GS} =0/15V			2.7		nC
Gate source charge 栅-源极电荷	Q _{GS}				4.2		
Gate-drain charge 栅-漏极电荷	Q _{GD}				8.5		
Turn-on delay time 开启延迟时间	t _{d(on)}	V _{GE} =0/15V V _{DD} =400V I _C =5A R _{G(ext)} =20Ω	T _{vj} =25°C		8.7		ns
			T _{vj} =175°C		8.2		
Rise time 上升时间	t _r		T _{vj} =25°C		8.9		ns
			T _{vj} =175°C		9		
Turn-off delay time 关闭延迟时间	t _{d(off)}		T _{vj} =25°C		9.1		ns
			T _{vj} =175°C		10.1		
Fall time 下降时间	t _f		T _{vj} =25°C		12		ns
			T _{vj} =175°C		12.9		
Turn-on switch loss 单次开启损耗	E _{on}		T _{vj} =25°C		33.6		μJ
			T _{vj} =175°C		34.6		
Turn-off switch loss 单次关闭损耗	E _{off}		T _{vj} =25°C		0.3		μJ
			T _{vj} =175°C		0.4		

Table 5 Reverse diode characteristics/体二极管反向特性

Parameter 参数	Symbol 符号	Test conditions 测试条件	Value/值			Unit 单位
			Min.	Typ.	Max.	
Drain-source reverse voltage 体二极管正向压降	V_{SD}	$I_S=2.5A, V_{GS}=0V$	$T_{vj}=25^\circ C$	3.2		V
			$T_{vj}=175^\circ C$	3		
MOSFET forward recovery time MOSFET正向恢复时间	t_{fr}	$V_{GS}=0V, V_{DS}=400V$, $I_S=5A$, $R_{G(ext)}=20\Omega$ $T_{vj}=175^\circ C$		11.5		ns
MOSFET forward recovery charge MOSFET正向恢复电荷	Q_{fr}			6.9		nC
MOSFET peak forward recovery current MOSFET正向恢复峰值电流	I_{frm}			2		A



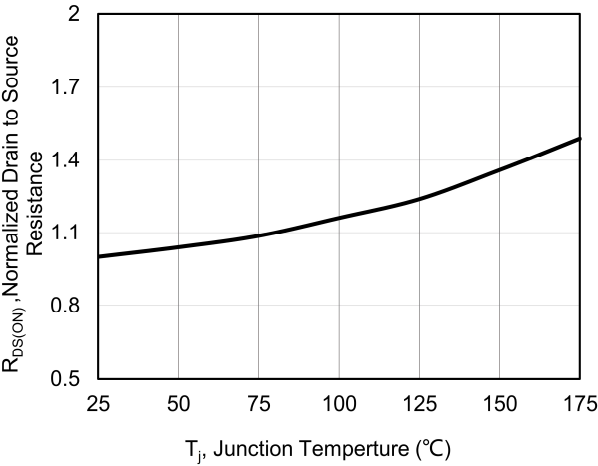
4. Electrical characteristics diagrams
电气特性图表

Power dissipation/耗散功率 $P_{tot}=f(T_c)$; 	Continuous Drain Current/连续漏电流与壳温 $I_{DS}=f(T_c)$; 
Typ.Output characteristic/典型输出特性 $I_{DS}=f(V_{DS})$; $T_{vj}=25^{\circ}\text{C}$ 	Typ.Output characteristic/典型输出特性 $I_{DS}=f(V_{DS})$; $T_{vj}=175^{\circ}\text{C}$ 

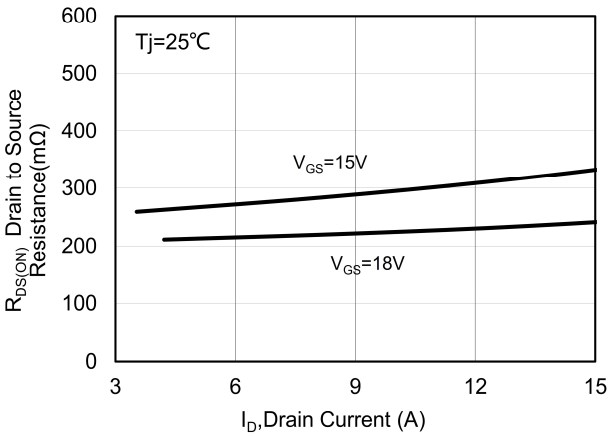
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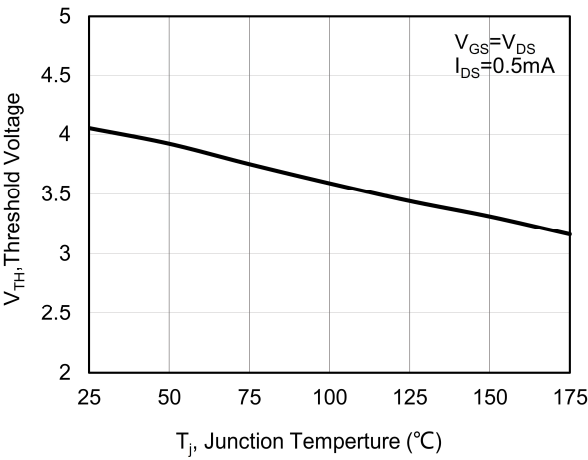
Typ.Drain-source on-state resistance/漏源导通电阻
 $R_{DS(on)}=f(T_j)$;



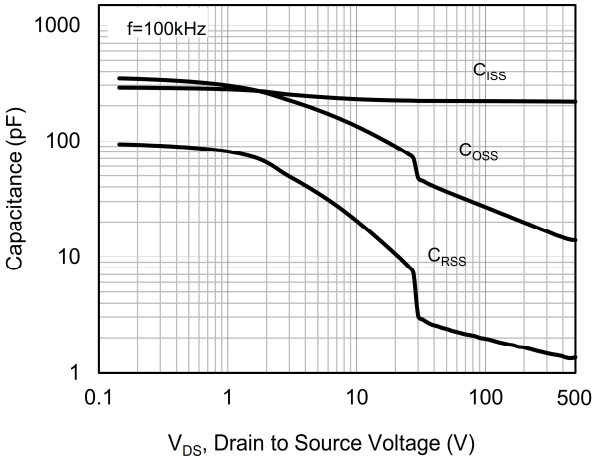
Typ.Drain-source on-state resistance/漏源导通电阻
 $R_{DS(on)}=f(I_{DS})$;



Typ.Gate threshold voltage/门级阈值电压结温特性
 $V_{Gsth}=f(T_j)$;



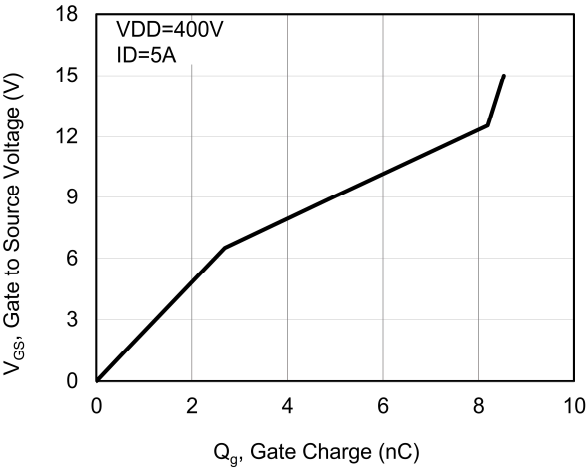
Typ. Capacitances/典型电容特性
 $C=f(V_{DS}); V_{GS}=0\text{V}$



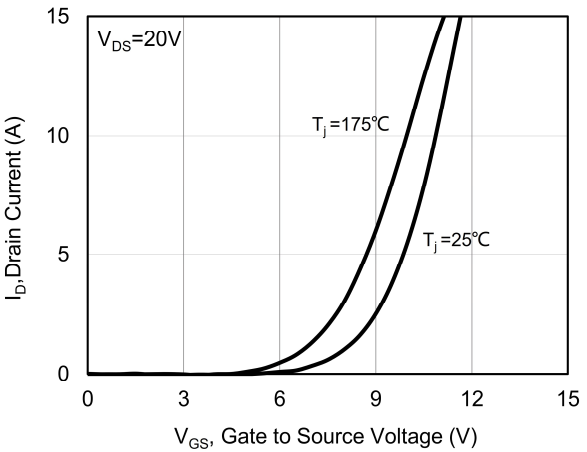
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HC260N075H6Y



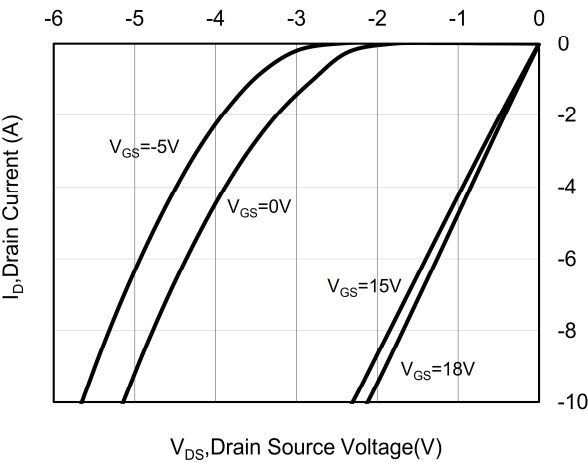
Typ. Gate charge/典型门级电荷
 $V_{GS}=f(Q_G)$;



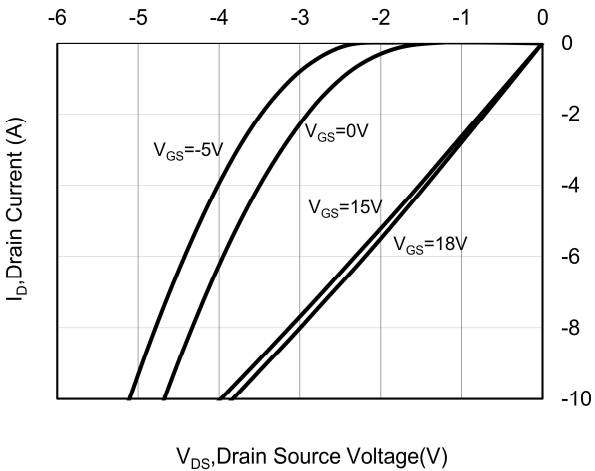
Typ. Transfer characteristics/传输特性
 $I_{DS}=f(V_{GS})$;



Typ. Reverse drain current characteristics/典型二极管特性
 $I_{SD}=f(V_{SD})$; $T_{vj}=25^\circ C$



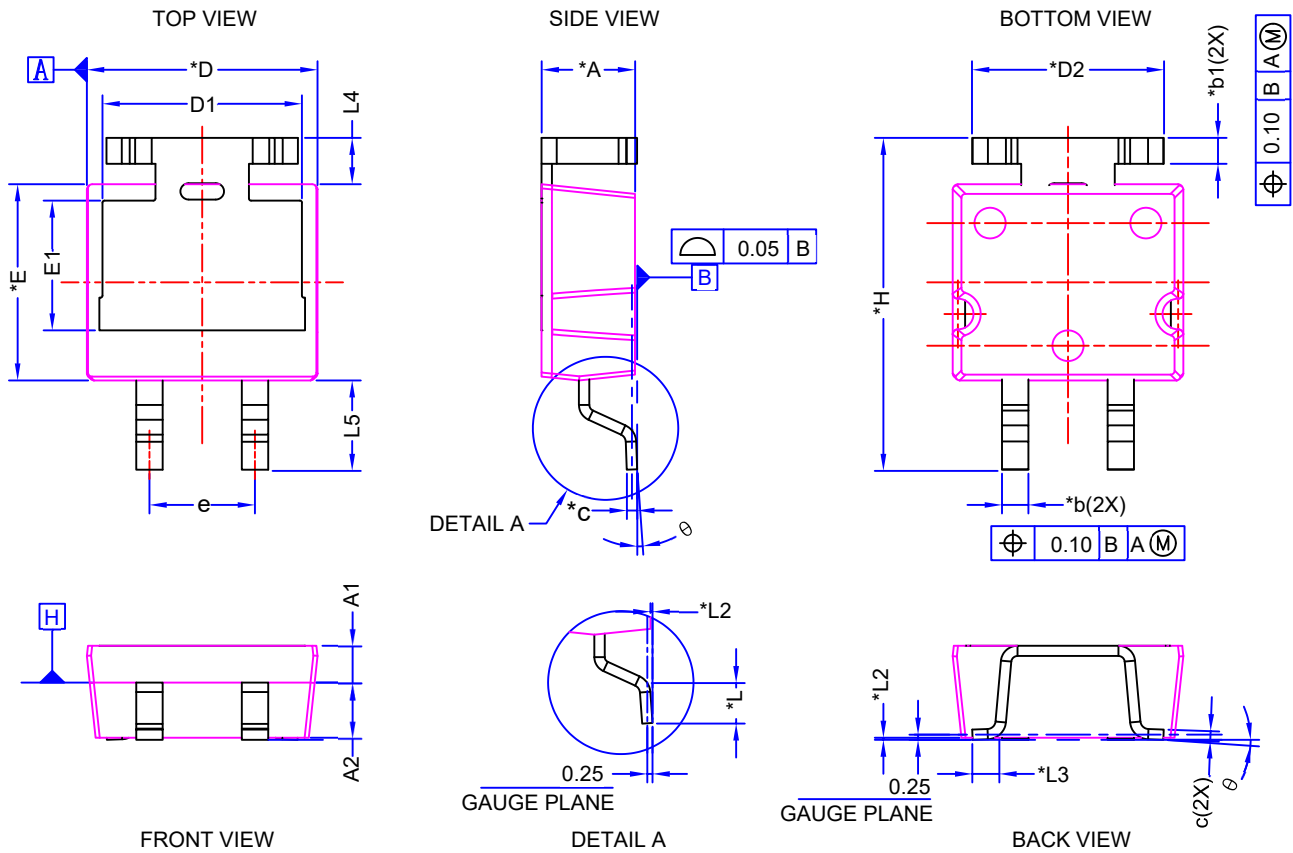
Typ. Reverse drain current characteristics/典型二极管特性
 $I_{SD}=f(V_{SD})$; $T_{vj}=175^\circ C$



5. Package outline

封装外形

Figure 1. Outline TSC263-4L, dimensions in mm/TSC263-4L外形尺寸 (毫米)



DIM SYMBOL	MIN.	TYP.	MAX.	DIM SYMBOL	MIN.	TYP.	MAX.
*A	4.40	4.50	4.60	*E	9.45	9.60	9.75
A1	1.75	1.80	1.85	E1	6.15	6.35	6.55
A2	2.65	2.70	2.75	e	5.08 BSC		
*b	1.22	1.27	1.32	*H	16.02	16.22	16.42
*b1	1.22	1.27	1.32	*L	1.70	1.90	2.10
*c	0.45	0.50	0.55	*L2	0.05	0.10	0.15
*D	10.95	11.10	11.25	*L3	1.10	1.30	1.50
D1	9.50	9.60	9.70	L4	2.27 REF		
*D2	9.00	9.20	9.40	L5	4.15	4.35	4.55
				Θ	0°	-	8°

NOTES:

- ALL DIMENSIONS ARE IN MILLIMETER. ANGLES ARE IN DEGREE.
- DIMENSION "D" DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH SHALL NOT EXCEED 0.150 MM PER SIDE. DIMENSION "E" DOES NOT INCLUDE MOLD FLASH, GATE BURRS, THE GATE BURRS SHALL NOT EXCEED 0.15MM.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

注:

- 所有尺寸均以毫米为单位。角度以度为单位。
- 尺寸 D 不包括引脚间飞边或突出物。引脚间飞边在每侧不得超过0.15mm。尺寸 E 不包括模具飞边、浇口残余物，浇口残余物不得超过0.15mm。
- 尺寸 D、E 是在塑胶本体的最外极限确定的，不包括模具飞边、连接条残余、浇口残余和引脚间飞边，但包括塑胶本体顶部和底部之间可能存在的任何不匹配或错位。

推荐焊盘尺寸

[illegible]

dimensions in mm/单位为毫米

注：
所示焊盘尺寸仅供参考。为确保最佳散热性能及焊接质量，建议根据实际应用中的 PCB 板材、层数及散热设计对焊盘进行优化调整
The land pattern dimensions provided are for reference only. To achieve optimal thermal performance, actual design adjustments should be considered based on the specific PCB materials, layer stack-up, and thermal dissipation requirements.



7. Revision history

修订历史

Table 6 Date and version number/日期与版本号

Date日期	Revision版本	Changes更改内容
2026-08-28	Rev.G 1.0	Target Datasheet (目标规格书)

8. Matters needing attention

注意事项

Appendix 1. Important Technical Guidance, Application Policy, and Copyright Notice/重要技术指南、应用规范与版权声明

[Data and Design Guidance]

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